



EMB2F THRU EMB8F

GLASS PASSIVATED SUPER FAST RECOVERY BRIDGE RECTIFIERS

Voltage Range - 200 to 600Volts Current - 0.8/1.0 Ampere

FEATURES

Ideal for printed circuit board
 Reliable low cost construction utilizing
 molded plastic technique
 High temperature soldering guaranteed:
 260°C/10 seconds at 5 lbs., (2.3kg) tension
 Small size, simple installation
 Leads solderable per MIL-STD-202, Method 208
 High surge current capability
 Super fast switching for high efficiency
 Glass passivated chip junction
 Green compound(halogen&Sb₂O₃ free)

MECHANICAL DATA

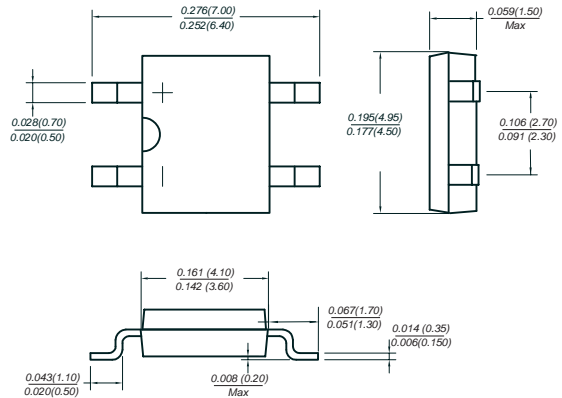
Case: Molded plastic body

Terminals: Plated leads solderable per MIL-STD-750,
 Method 2026

Polarity: Polarity symbols marked on case

Mounting Position: Any

MBF



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	EMB2F	EMB4F	EMB6F	EMB8F	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	100	200	400	600	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	V
Maximum DC blocking voltage	V_{DC}	100	200	400	600	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	$I_{F(AV)}$		0.8 1.0			A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}		30			A
Maximum instantaneous forward voltage drop per leg at 0.4A	V_F	0.95		1.25	1.7	V
Maximum DC reverse current $T_A=25^\circ C$ at rated DC blocking voltage $T_A=125^\circ C$	I_R		5.0 500			μA μA
Typical thermal resistance(NOTE 3)	$R_{\theta JL}$ $R_{\theta JA}$		30 88			$^\circ C/W$
Maximum reverse recovery time (NOTE 4)	t_{rr}		35			ns
Operating temperature range	T_J		-55 to +150			$^\circ C$
storage temperature range	T_{STG}		-55 to +150			$^\circ C$

NOTES:1. On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.

2. On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.

3. Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

4. Reverse recovery condition $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$.



RATINGS AND CHARACTERISTIC CURVES EMB2F THRU EMB8F

FIG.1 FORWARD DERATING CURVE

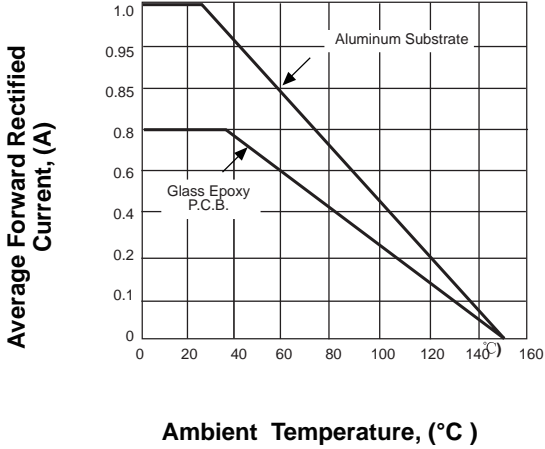


FIG.2 PEAK FORWARD SURGE CURRENT

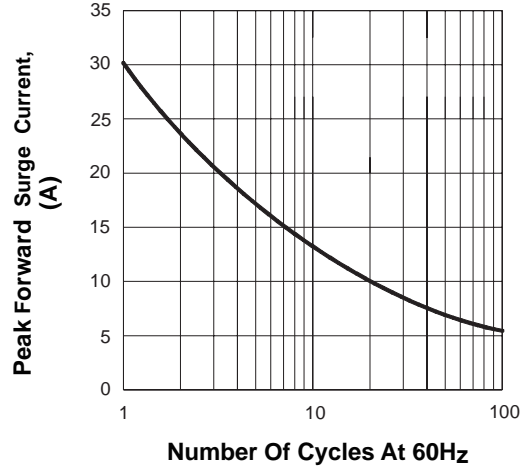


FIG.3 TYPICAL FORWARD CHARACTERISTICS

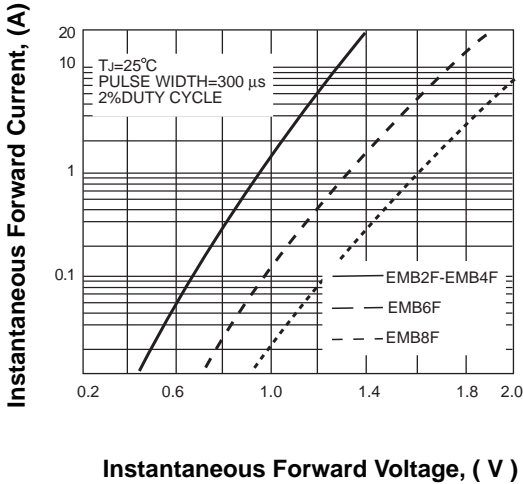
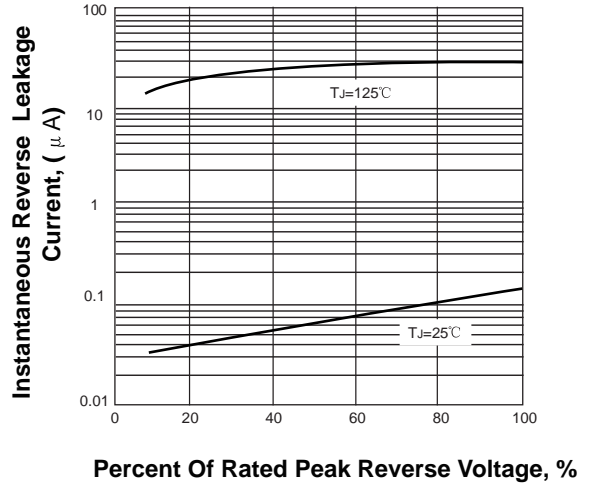


FIG.4 TYPICAL REVERSE CHARACTERISTICS



单击下面可查看定价，库存，交付和生命周期等信息

[>>ZG\(中鑫半导体\)](#)